

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	2167	(dual with damascene) and (barrier with etch\$3)	US-PGPUB; USPAT	OR	ON	2005/06/10 10:38
S2	1159	S1 and (plasma with etch\$3)	US-PGPUB; USPAT	OR	ON	2005/06/10 17:00
S3	1	("5904565").PN.	USPAT	OR	OFF	2005/06/10 11:46
S4	18	(US-20020064941-\$ or US-20020106895-\$ or US-20040121616-\$ or US-20050064708-\$ or US-20050118796-\$).did. or (US-5904565-\$ or US-6023102-\$ or US-6150723-\$ or US-6274008-\$ or US-6284657-\$ or US-6300236-\$ or US-6323131-\$ or US-6329290-\$ or US-6372636-\$ or US-6410437-\$ or US-6429122-\$ or US-6607977-\$ or US-6878615-\$).did.	US-PGPUB; USPAT	OR	ON	2005/06/10 13:01
S5	1	S4 and remote	US-PGPUB; USPAT	OR	ON	2005/06/10 12:59
S6	326	remote with plasma with etch\$3	USPAT	OR	ON	2005/06/10 13:02
S7	18	S6 and (dual with damascene)	USPAT	OR	ON	2005/06/10 13:12
S8	15	S7 and (remote with plasma with etch)	USPAT	OR	ON	2005/06/10 13:16
S9	0	S4 and (remote with plasma with etch)	USPAT	OR	ON	2005/06/10 13:16
S10	177	(remote with plasma with etch)	USPAT	OR	ON	2005/06/10 13:16
S11	255	"1" and (etch with stop with composite)	US-PGPUB; USPAT	OR	ON	2005/06/10 17:01
S12	49	(dual with damascene) and (barrier with etch\$3) and (etch with stop with composite)	US-PGPUB; USPAT	OR	ON	2005/06/10 18:32
S13	27	(composite or graded or (dual adj layer) or multilayer) adj (etch adj stop)	US-PGPUB; USPAT	OR	ON	2005/06/10 18:43
S14	396	(composite or graded or (dual adj layer) or multilayer) with (etch adj stop)	US-PGPUB; USPAT	OR	ON	2005/06/10 18:43
S15	119	S14 and damascene	US-PGPUB; USPAT	OR	ON	2005/06/12 14:08
S16	113	(ion adj metal adj plasma) with deposition	USPAT	OR	ON	2005/06/12 14:09
S17	57	S16 and damascene and barrier	USPAT	OR	ON	2005/06/12 15:42
S18	8882	438/622,637,638,643,644,656,660,666,672,686,687,706,707.ccls.	US-PGPUB; USPAT	OR	ON	2005/06/12 15:48

S19	866	S18 and barrier and damascene and (etch with stop)	US-PGPUB; USPAT	OR	ON	2005/06/12 15:49
S20	1046	438/643.ccls.	US-PGPUB; USPAT	OR	ON	2006/02/05 14:59

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	0	(substrate and (dielectric or insulat\$3) and ((etch adj stop) with (plurality or multiple)) and (dual adj damascene) and via and trench and (barrier with (remov\$3 or etch\$3) with plasma) and (copper or Cu)).CLM.	US-PGPUB	OR	ON	2006/02/06 10:17
L2	0	(substrate and (dielectric or insulat\$3) and ((etch adj stop) with (plurality or multiple)) and (dual adj damascene) and via and trench and (barrier with plasma) and (copper or Cu)).CLM.	US-PGPUB	OR	ON	2006/02/06 10:16
L3	0	(substrate and (dielectric or insulat\$3) and ((etch adj stop) with (plurality or multiple)) and (dual adj damascene) and via and trench and (barrier with (remov\$3 or etch\$3)) and (copper or Cu)).CLM.	US-PGPUB	OR	ON	2006/02/06 10:18
L4	0	(substrate and (dielectric or insulat\$3) and ((etch adj stop) with multiple) and (dual adj damascene) and via and trench and (barrier with (remov\$3 or etch\$3)) and (copper or Cu)).CLM.	US-PGPUB	OR	ON	2006/02/06 10:18
L5	1	(substrate and dielectric and (etch adj stop) and multiple and (dual adj damascene) and via and trench and (barrier with (remov\$3 or etch\$3)) and (copper or Cu)).CLM.	US-PGPUB	OR	ON	2006/02/06 10:19